

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10750021			
<b>Filing Date:</b>	30-Dec-2003			
<b>Title of Invention:</b>	Method for fabricating semiconductor device having trench type device isolation layer			
<b>First Named Inventor/Applicant Name:</b>	Tae-Woo Jung			
<b>Filer:</b>	Stacie Jo Sundquist/Si Vuong			
<b>Attorney Docket Number:</b>	51876P542			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1202	5	50	250
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1020	1020
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1270</b>